

Title (en)  
Bamboo board and method of producing the same

Title (de)  
Bambusplatte und Verfahren zu deren Herstellung

Title (fr)  
Panneau de bambou et son procédé de fabrication

Publication  
**EP 1043131 A1 20001011 (EN)**

Application  
**EP 99302526 A 19990331**

Priority  
EP 99302526 A 19990331

Abstract (en)  
A process for making a bamboo board includes the steps of obtaining thin bamboo chips (21) by planing bamboo stems along the direction of the orientation of bamboo fibers, drying the bamboo chips to remove water so that the water content in the bamboo chips is reduced to 6%-10% by weight, mixing the dried bamboo chips with at least one additive selected from the group consisting of a water-proofing agent and a fire-retarding agent, blending the mixture of the bamboo chips and the additive with a binder so as to bind the bamboo chips, forming the bound bamboo chips into a board under pressure and temperature, and covering the surfaces of the board with facing sheets. <IMAGE>

IPC 1-7  
**B27N 3/00**; **B27N 9/00**; **B27N 7/00**

IPC 8 full level  
**B27N 3/00** (2006.01); **B27N 7/00** (2006.01); **B27N 9/00** (2006.01)

CPC (source: EP)  
**B27N 3/00** (2013.01); **B27N 7/005** (2013.01); **B27N 9/00** (2013.01)

Citation (applicant)  
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Citation (search report)  
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• [Y] EP 0255950 A2 19880217 - HOMANIT GMBH & CO KG [DE], et al  
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